

## Lonten N-channel 30V, 5.8A, 26mΩ Power MOSFET

## **Description**

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and with stand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

#### **Features**

- $30V,5.8A,R_{DS(ON).max}=26m\Omega@V_{GS}=10V$
- Improved dv/dt capability
- ♦ Fast switching
- Green device available

### **Applications**

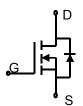
- PWM application
- Load switch
- Power management

### **Product Summary**

 $\begin{array}{ll} V_{DSS} & 30V \\ R_{DS(on).max} \textcircled{0} \ V_{GS} \text{=} 10V & 26m\Omega \\ I_D & 5.8A \end{array}$ 

### **Pin Configuration**





SOT-23

N-Channel MOSFET



#### Absolute Maximum Ratings T<sub>A</sub> = 25°C unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DSS</sub>	30	V
Continuous drain current ( T <sub>A</sub> = 25°C )		5.8	A
Continuous drain current ( T <sub>A</sub> = 100°C )	l <sub>D</sub>	3.7	A
Pulsed drain current <sup>1)</sup>	Ірм	23.2	А
Gate-Source voltage	V <sub>GSS</sub>	±12	V
Power Dissipation ( T <sub>A</sub> = 25°C )	P <sub>D</sub>	1.4	W
Storage Temperature Range	T <sub>STG</sub>	-55 to +150	°C
Operating Junction Temperature Range	TJ	-55 to +150	°C

#### **Thermal Characteristics**

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Ambient	$R_{ heta JA}$	89	°C/W



**Package Marking and Ordering Information** 

Device	Device Package	Marking		
LNSC3400	SOT-23	3400		

Flectrical	Characteristics	T <sub>.1</sub> = 25°C unless otherwise noted
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Parameter	Symbol	Test Condition	Min.	Тур.	Max.	Unit
Static characteristics						
Drain-source breakdown voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0 V, I <sub>D</sub> =250uA	30			V
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA	0.65	1.0	1.35	V
		V <sub>DS</sub> =30 V, V <sub>GS</sub> =0 V, T <sub>J</sub> = 25°C			1	μA
Drain-source leakage current	I <sub>DSS</sub>	V <sub>DS</sub> =24 V, V <sub>GS</sub> =0 V, T <sub>J</sub> = 125°C			10	μA
Gate leakage current, Forward	I <sub>GSSF</sub>	V <sub>GS</sub> =12 V, V <sub>DS</sub> =0 V			100	nA
Gate leakage current, Reverse	I <sub>GSSR</sub>	V <sub>GS</sub> =-12 V, V <sub>DS</sub> =0 V			-100	nA
		V <sub>GS</sub> =10 V, I <sub>D</sub> =5.8 A		18	26	mΩ
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =4.5 V, I <sub>D</sub> =5 A		20	32	mΩ
		Vgs=2.5V, Id=4A		31	52	mΩ
Forward transconductance	<b>g</b> fs	V <sub>DS</sub> =5 V , I <sub>D</sub> =5.8A		30		S
Dynamic characteristics				•		
Input capacitance	C <sub>iss</sub>			494		
Output capacitance	Coss	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V},$ $F = 1 \text{MHz}$		62.4		pF
Reverse transfer capacitance	Crss	- 1 - 11/11/12		53.7		
Gate resistance	Rg	V <sub>GS</sub> =0V,V <sub>DS</sub> =0V,f=1MHz		4.2		mΩ
Turn-on delay time	t <sub>d(on)</sub>			7.6		
Rise time	tr	$V_{DD}$ = 15V, $V_{GS}$ =10V, $I_{D}$ =5.8 A, Rg=10 $\Omega$		113.2		]
Turn-off delay time	t <sub>d(off)</sub>			44.4		ns
Fall time	tf			13.6		
Gate charge characteristics						
Gate to source charge	Q <sub>gs</sub>			3.3		
Gate to drain charge	Q <sub>gd</sub>	$V_{DS}$ =15V, $I_{D}$ =5.8A, $V_{GS}$ = 10V		2.1		nC
Gate charge total	Qg	- VGS- 10V		13.6		
Drain-Source diode characteris	tics and Maxi	num Ratings			•	
Continuous Source Current	Is				5.8	Α
Pulsed Source Current <sup>2)</sup>	Ism				23.2	А
Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =5.8A, T <sub>J</sub> =25℃			1.2	V
				1	1	

### Notes:

<sup>1:</sup> Repetitive Rating: Pulse width limited by maximum junction temperature.

<sup>2:</sup> Pulse Test: Pulse Width  $\leq 300 \mu s$ , Duty Cycle  $\leq 2\%$ .



## **Electrical Characteristics Diagrams**

Figure 1. Typ. Output Characteristics

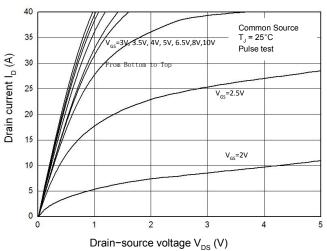


Figure 2. Transfer Characteristics

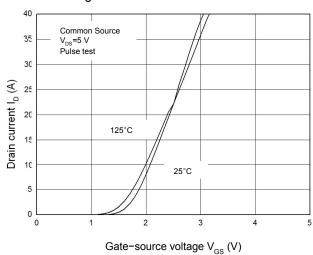


Figure 3. Capacitance Characteristics

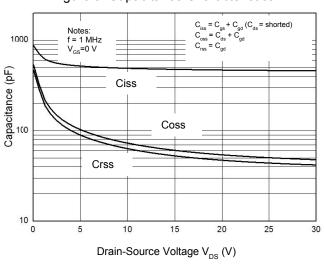


Figure 4. Gate Charge Waveform

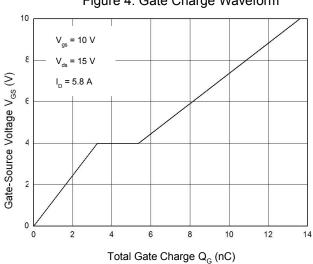


Figure 5. Body-Diode Characteristics

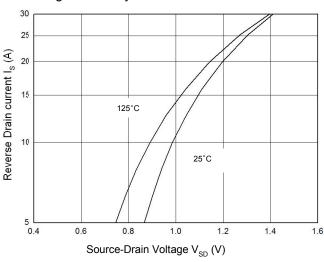


Figure 6. Rdson-Drain Current

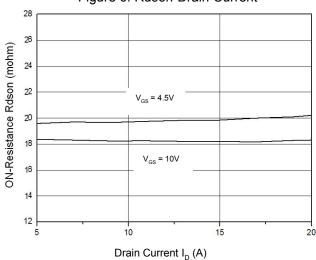




Figure 7. Rdson-Junction Temperature(℃)

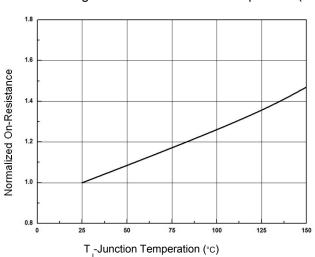


Figure 8. Maximum Safe Operating Area

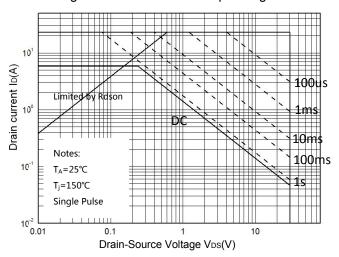
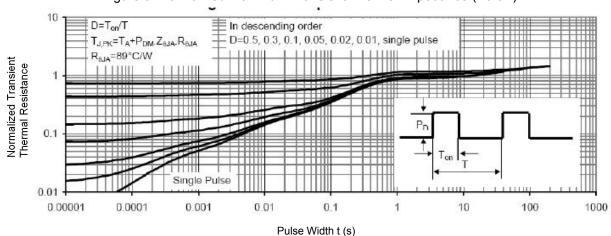


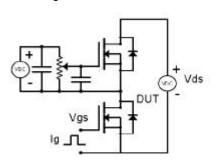
Figure 9. Normalized Maximum Transient Thermal Impedance (RthJA)





## **Test Circuit & Waveform**

Figure 8. Gate Charge Test Circuit & Waveform



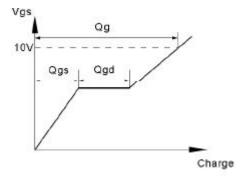
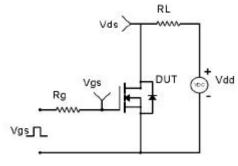


Figure 9. Resistive Switching Test Circuit & Waveforms



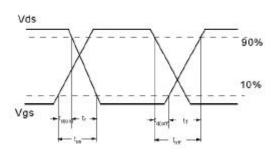
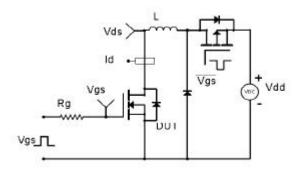


Figure 10. Unclamped Inductive Switching (UIS) Test Circuit & Waveform



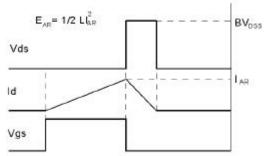
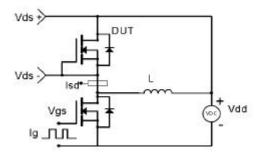
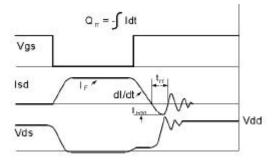


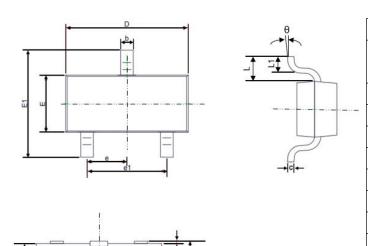
Figure 11. Diode Recovery Circuit & Waveform





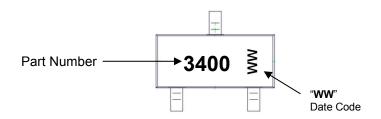


# **Mechanical Dimensions for SOT-23**



COMMON DIMENSIONS					
SYMBOL	MILLIMETERS		INCHS		
	MIN	MAX	MIN	MAX	
А	0.90	1.20	0.035	0.047	
A1	0.00	0.10	0.000	0.004	
A2	0.90	1.10	0.035	0.043	
b	0.39	0.45	0.015	0.018	
С	0.08	0.15	0.003	0.006	
D	2.80	3.00	0.110	0.118	
E	1.20	1.40	0.047	0.055	
E1	2.30	2.50	0.091	0.098	
е	0.95 TYP.		0.037 TYP.		
e1	1.90 REF.		0.075 REF.		
L	0.55 REF.		0.022 REF.		
L1	0.20	-	0.008	-	
θ	0°	10°	0°	10°	

## **SOT-23 Part Marking Information**





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